

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate (As Amended)

RESPONSE TO DECEMBER 9, 1999 OFFICE ACTION

To: Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828

Sir:

Responsive to the Office Action dated December 9, 1999,
Applicant amends and remarks as follows [unless otherwise indicated,
deletions are bracketed, additions are underlined]:

AMENDMENTS

RECEIVED
MAR 14 2000
TECHNOLOGY CENTER 3700